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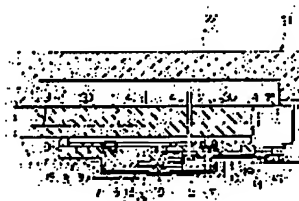
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TERAOKA SEIICHI**(54) HEATING TREATMENT FOR SUBSTRATE****(57)Abstract:**

PURPOSE: To make an apparatus small-sized by a method wherein, when a substrate to be treated is heat-treated by using heat of a heating plate at a second temperature after a heat treatment at a first temperature, an interval between the heating plate and the substrate to be treated is changed and the substrate is set to the second treatment temperature.

CONSTITUTION: A heating plate 2 is set in advance to a prescribed temperature; in a stage that pins 4 protrude on the heating plate 2, a semiconductor wafer 3 is placed on the pins 4. Then, the pins 4 are lowered; the wafer 3 is placed on proximity pins 20. A heating operation is executed for a prescribed time; a stepping motor 15 is driven; the pins 4 are raised; the wafer 3 is delivered from the pins 20 to the pins 4; a proximity gap is set to a prescribed value; a heating operation is executed for a prescribed time. When a treatment temperature is to be changed further, the pins 4 are moved up and down, and the proximity gap is changed and adjusted. Thereby, the treatment temperature of the semiconductor wafer 2 can be set to a desired temperature without changing a temperature of a heating plate 1.



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